IEC 62951-3

Edition 1.0 2018-11

INTERNATIONAL STANDARD

colour inside

Semiconductor devices – Flexible and strechable semiconductor devices – Part 3: Evaluation of thin film transistor characteristics on flexible substrates under bulging

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

ICS 31.080.99

ISBN 978-2-8322-6161-3

CONTENTS

INTERNATIONAL ELECTROTECHNICAL COMMISSION

_____

SEMICONDUCTOR DEVICES – FLEXIBLE AND STRECHABLE SEMICONDUCTOR DEVICES –

Part 3: Evaluation of thin film transistor characteristics on flexible substrates under bulging

FOREWORD

1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
6) All users should ensure that they have the latest edition of this publication.
7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.

International Standard IEC 62951-3 has been prepared by IEC technical committee 47: Semiconductor devices.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47/2492/FDIS	47/2511/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62951 series, published under the general title *Semiconductor devices – Flexible and stretchable semiconductor devices*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

The International Electrotechnical Commission (IEC) draws attention to the fact that it is claimed that compliance with this document may involve the use of a patent concerning the method and apparatus for testing flexible elements.

IEC takes no position concerning the evidence, validity and scope of this patent right.

The holder of this patent right has assured the IEC that he/she is willing to negotiate licences under reasonable and non-discriminatory terms and conditions with applicants throughout the world. In this respect, the statement of the holder of this patent right is registered with IEC. Information may be obtained from:

Industry Academy Cooperation Foundation of Sejong University,
Korea Institute of Machinery and Materials,
Electronics and Telecommunications Research Institute
1002 GwangGaeTo B/D
209, Neungdong-ro, Gwangjin-gu, Seoul, 05006,
KOREA

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights other than those identified above. IEC shall not be held responsible for identifying any or all such patent rights.

ISO (www.iso.org/patents) and IEC (http://patents.iec.ch) maintain on-line data bases of patents relevant to their standards. Users are encouraged to consult the data bases for the most up to date information concerning patents.

SEMICONDUCTOR DEVICES – FLEXIBLE AND STRECHABLE SEMICONDUCTOR DEVICES –

Part 3: Evaluation of thin film transistor characteristics on flexible substrates under bulging

1 Scope

This part of IEC 62951 specifies the method for evaluating thin film transistor characteristics on flexible substrates under bulging. The thin film transistor is fabricated on flexible substrates, including polyethylene terephthalate (PET), polyimide (PI), elastomer and others. The stress is applied by applying a uniformly-distributed pressure to the flexible substrate using the equipment.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 62047-17, *Semiconductor devices – Micro-electromechanical devices – Part 17: Bulge test method for measuring mechanical properties of thin films*

IEC 60747-8, *Semiconductor devices – Discrete devices – Part 8: Field-effect transistors*